THE COMMISSIONER OF PATENTS AND TRADEMARKS WASHINGTON, D.C. 20231

02/25/02

 \Box Sir:

Transmitted herewith for filing is the Utility patent application of:

INVENTOR:	Souichi KATAGIRI, Ui YAMAGUCHI, Seiichi KONDO, Kan

YASUI and Yoshio KAWAMURA

FOR: METHOD AND APPARATUS FOR MANUFACTURING

SEMICONDUCTOR DEVICE

Enclosed are:

- 6 sheets of □ formal □ informal drawings.
- ☐ An assignment of the invention to __
- ☑ An Information Disclosure Statement with PTO Form 1449
- ☑ An Unexecuted Declaration

☑ The filing fee is calculated as shown below:

For	Number	R FILED	Number Extra	RATE	CALCULATIONS
TOTAL CLAIMS	19	-20	0	x\$18 =	0.00
INDEPENDENT CLAIMS	4	-3	1	x\$84 =	84.00
MULTIPLE DEPENDENT CLAIM(S) (if applicable) +\$280 =					\$0.00
		¥	BASIC FEE		\$740.00
			TOTAL OF ABOVE		824.00
REDUCTION BY ½ FOR FILE					
IF APPLICABLE, VERIFIED	STATEMENT	UST BE ATTAC	neu	TOTAL	824.00

Please charge my Deposit Account Number	in the amount of	to cover the filing and assignment recordation
fees. A duplicate copy of this paper is enclosed.		

- A check in the amount of \$824.00 to cover the filing fees is enclosed.
- The Commissioner is hereby authorized to charge any additional fees associated with this communication, including patent application filing fees and processing fees under 37 C.F.R. § 1.16 and 1.17, or credit any overpayment to **Deposit Account Number 08-1480**.

Respectfully submitted

Stapley P. Fisher

Registration Number 24,344

JUAN CARLOS A. MARQUEZ Registration No. 34,072

REED SMITH LLP 3110 Fairview Park Drive Suite 1400 Falls Church, Virginia 22042 (703) 641-4200

February 25, 2002

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In re U.S. Patent Application of)
KAT.	AGIRI et al.)
Appli	cation Number: To be assigned)
Filed:	Concurrently Herewith)
For:	METHOD AND APPARATUS FOR)
	MANUFACTURING SEMICONDUCTOR DEVICE)

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

REQUEST FOR PRIORITY UNDER 35 U.S.C. § 119 AND THE INTERNATIONAL CONVENTION

Sir:

In the matter of the above-captioned application for a United States patent, notice is hereby given that the Applicant claims the priority date of April 25, 2001, the filing date of the corresponding Japanese patent application 2001-127043.

The certified copy of corresponding Japanese patent application 2001-127043 will be submitted as soon as received from Applicant. Acknowledgment of receipt of the certified copy is respectfully requested in due course.

Respectfully submitted,

Startley P. Fisher

Registration Number 24,344

JUAN CARLOS A. MARQUEZ Registration No. 34,072

REED SMITH LLP

3110 Fairview Park Drive Suite 1400 Falls Church, Virginia 22042 (703) 641-4200 February 25, 2002



List of prior references

- 1. Japanese Patent Laid-Open Hei 2-278822:
 (Attached U.S.P. No. 4,954,142 and U.S.P. No. 5,084,071 being corresponded to Japanese Patent Laid-Open Hei 2-278822)
- Japanese Patent Laid-Open Hei 8-83780:
 (Attached U.S.P. No. 5,770,095 being corresponded to Japanese Patent Laid-Open Hei 8-83780)
- 3. "2000 Chemical Mechanical Planarization for ULSI Multilevel Interconnection Conference", in pp. 58 65:
- 4. U.S.P. No. 5,972,792:
- 5. "New Material and Process Technology for Next Generation ULSI Multi-layered Wirings", by technical information society, in pp. 242 246:
- 6. Japanese Patent Laid-Open 2000-49122: (Attached Patent Abstracts of Japan)